

# Abstract

Test apparatus for testing a semiconductor device having contact pads on its top and its bottom, and method for testing the semiconductor device

The invention relates to a test apparatus (1) for testing a semiconductor device (2) having contact pads (3) on its top (4) and its back (5), and to a method for testing the semiconductor device (2). To this end, the test apparatus (1) has a test socket (8) which is mounted on a test printed circuit board (6). Internal through-contact elements (10) of the test socket (8) can be used to test contact pads (3) on the top (4) of the semiconductor device (2). The contact pads (3) on the back (5) of the semiconductor device (2) can be connected for the purpose of testing the semiconductor device (2) using external through-contact elements (12) which are arranged outside of the locating seat (9).

[Figure 1]